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In the Claims

Amendments to the Claims:

1. (currently amended) A method of forming a substantially planar surface of an optical waveguide device, comprising the steps:

forming at least one waveguide core portion within at least one cladding portion; the waveguide core portion having an upper surface; the cladding portion having a higher portion over at least the waveguide core portion and a lower portion;

forming a patterned sacrificial portion over the lower cladding portion and a portion of the higher cladding portion, leaving a second portion of the higher cladding portion exposed;

removing at least a portion of the exposed second portion of the higher cladding portion by a selective removal process selective to the patterned sacrificial portion leaving a remnant of the exposed second portion of the higher cladding portion; and

planarizing:

- a) the remnant of the exposed second portion of the higher cladding portion over the waveguide core portion; and
 - b) the lower cladding portion[;]

to form a planarized cladding portion coplanar with the upper surface of the

waveguide core portion[;]

20 to form the substantially planar surface of an optical waveguide device.

2. (previously presented) The method of claim 1, wherein the planarized

cladding portion has a thickness of between about 0 and 200 nm above the upper

surface of the waveguide core portion.

3. (original) The method of claim 1, wherein the cladding portion has a first index

of refraction; the waveguide core portion has a second index of refraction; and

the waveguide core portion second index of refraction is greater than the

cladding portion first index of refraction.

4. (original) The method of claim 1, wherein the planarization is a chemical

mechanical polishing process.

5. (original) The method of claim 1, wherein the waveguide core portion

comprises at least one waveguide core embedding within at least another

waveguide core.

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6. (original) The method of claim 1, wherein the patterned sacrificial portion is

comprised of:

photoresist: or

photoresist stacked upon a film comprised of: silicon nitride, silicon

oxynitride organic silicate glass, diamond like carbon, silicon dioxide, polyimide,

PMMA, tantalum, tungsten or molybdenum.

7. (original) The method of claim 1, wherein the cladding portion is comprised of

silicon nitride, organic silicate glass, silicon dioxide, polyimide or PMMA.

8. (original) The method of claim 1, wherein the selective removal process

selective to the patterned sacrificial portion is a dry and/or wet etching process.

9. (original) The method of claim 1, wherein the patterned sacrificial portion is

removed before the planarization.

10. (original) The method of claim 1, wherein the sacrificial portion is photoresist

and the patterned sacrificial photoresist portion is removed before the

planarization by a stripping process.

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11. (original) The method of claim 1, wherein the waveguide core portion is

formed using a first mask; and the patterned sacrificial portion is patterned from

a sacrificial layer using a second mask that is the reverse of the first mask.

12. (previously presented) The method of claim 1, wherein the planarization also

removes any remaining patterned sacrificial portion.

13. (original) The method of claim 1, wherein waveguide core portion is formed

using a first mask; and not all the sacrificial portion area is needed to be

patterned using a second mask that is the reverse of the first mask.

14. (original) The method of claim 1, wherein the patterned sacrificial portion is

also removed during the planarization.

15. (original) The method of claim 1, wherein the planarization includes a fine

planarization process.

16. (previously presented) The method of claim 1, wherein the planarization of

the remnant of the exposed second portion of the higher cladding portion over

the waveguide core portion and the lower cladding portion does not expose the

upper surface of the waveguide core portion.

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Claims 17 to 57 (canceled)

Claims 58 to 74 (canceled)